

Special Issue

The Fabrication of Microstructures from Powders and Their Applications in Microsystems

Message from the Guest Editor

This Special Issue seeks to showcase research papers and review articles that focus on: (1) powder-based techniques for 3D microstructure fabrication compatible to silicon, glass, ceramic or plastic substrates, panels or boards; (2) simulation and characterization of powder-based 3D microstructures fabricated from various materials; (3) fabrication, simulation and characterization of MEMS devices utilizing powder-based 3D microstructures; (4) novel functionalities and applications for MEMS due to powder-based 3D microstructures; (5) durability, reliability and long-term stability of powder-based 3D microstructures.

- powder-based techniques
- 3D microstructures
- MEMS

Guest Editor

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Message from the Editor-in-Chief

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